



**Materials Declaration**

<b>Package</b>	LFCSP
<b>Body Size</b>	6 X 6
<b>LeadCount</b>	40
<b>Option</b>	Pb Free

**Molding Compound**

Item	% of Compound	Weight (g)	PPM
Epoxy Resin	10	3.41 E-03	38379
SiO2 Filler	85	2.90 E-02	326220
Phenol Resin	5	1.71 E-03	19189

**Molding Compound**

Item	PPM	Method
Pb	4	EPA3050B (ICPAES)
Cd	<2	BSEN 1122:2001B (ICP AES)
Hg	<2	Mercury Analyser
Cr+6	<2	EPA3060A (UV)

**Leadframe**

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	4.49 E-02	504669
Fe	2.35	1.08 E-03	12164
P	0.03	1.38 E-05	155
Zn	0.12	5.52 E-05	621

**Die Attach Paste**

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	Not Detected	ICP AES

**Internal Leadframe Plating**

Item	% of Plating	Weight (g)	PPM
Ag	100	9.25 E-04	10403

**External Leadframe Plating**

Item	% of Plating	Weight (g)	PPM
Sn	100	2.76 E-04	3108

**Bond Wires**

Item	% of Wire	Weight (g)	PPM
Au	99.99	9.36 E-04	10529

**Chip**

Item	% of Chip	Weight (g)	PPM
Si	100	5.68 E-03	63923

**Die Attach**

Item	% of Die Attach	Weight (g)	PPM
Resin	25	2.36 E-04	2660
Ag Filler	75	7.09 E-04	7979

**Package Totals**

Weight (g)	PPM
<b>8.89 E-02</b>	<b>1000000</b>

AMK-CP-C

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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<b>Package</b>	LFCSP
<b>Body Size</b>	6 X 6
<b>LeadCount</b>	40
<b>Option</b>	Sn/Pb

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Epoxy Resin	10	3.41 E-03	38379
SiO2 Filler	85	2.90 E-02	326220
Phenol Resin	5	1.71 E-03	19189

Molding Compound		
Item	PPM	Method
Pb	4	EPA3050B (ICPAES)
Cd	<2	BSEN 1122:2001B (ICP AES)
Hg	<2	Mercury Analyser
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Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	4.49 E-02	504669
Fe	2.35	1.08 E-03	12164
P	0.03	1.38 E-05	155
Zn	0.12	5.52 E-05	621

Die Attach Paste		
Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	Not Detected	ICP AES

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100	9.25 E-04	10403

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	2.35 E-04	2642
Pb	15	4.14 E-05	466

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	9.36 E-04	10529

Chip			
	% of Chip	Weight (g)	PPM
Si	100	5.68 E-03	63923

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	25	2.36 E-04	2660
Ag Filler	75	7.09 E-04	7979

Package Totals	
Weight (g)	PPM
<b>8.89 E-02</b>	1000000

AMK-CP-A

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